In The Claims:

1-18. (Cancelled).

19. (New) A microphone component comprising:

at least one piezoelectric transflexural diaphragm element, and

a signal interface element comprising conductors, the signal interface element comprising a flexible printed circuit with a stiffness below that of the piezoelectric transflexural diaphragm element,

wherein an electrical and mechanical connection between the signal interface element and the piezoelectric transflexural diaphragm element is made of a material having an negligible electrical resistance with respect to an output resistance of the piezoelectric transflexural diaphragm element, a stiffness below that of the signal interface element, and being able to bond the signal interface element and the piezoelectric transflexural element to each other.

20. (New) A microphone component according to claim 19, wherein the material of which the electrical and mechanical connection is made is an anisotropic conducting polymer.

21. (New) A microphone component according to claim 20, wherein the anisotropic conducting polymer is in the form of an anisotropic conducting adhesive tape.

22. (New) A microphone component according to claim 21, wherein the anisotropic conducting polymer is a curable dispersion of conducting particles.

23. (New) A microphone component according to claim 19, wherein the signal interface element is connected to the piezoelectric transflexural diaphragm element by means of a conductive adhesive tape patterned to correspond to terminal areas on the piezoelectric transflexural diaphragm element.

24. (New) A microphone component according to claim 21, further comprising a supporting resilient layer on at least one side of an assembly formed of the piezoelectric transflexural diaphragm element, anisotropic conducting adhesive tape and interface element.

25. (New) A microphone component according to claim 24, wherein a mechanically protective front surface is provided on an outer side of the supporting resilient layer.

26. (New) A microphone component according to claim 25, wherein the mechanically protective front surface is an elastic disc of essentially the same dimensions as the piezoelectric transflexural diaphragm element.

27. (New) A microphone component according to claim 26, wherein the elastic disc is a metal disc having resilient characteristics.

28. (New) A microphone component according to claim 24, wherein the resilient layer is comprised of an elastomeric foam pad.

29. (New) A microphone component according to claim 28, wherein the foam pad has an adhesive layer thereon that is protected by a removable cover the foam pad being adapted to be removably fixed in a cavity after removal of said cover.

30. (New) A microphone component according to claim 19, wherein the printed circuit carries at least one impedance converting component in proximity to the piezoelectric transflexural diaphragm element.

31. (New) A microphone component according to claim 19, wherein said piezoelectric transflexural diaphragm element is one of a plurality of piezoelectric transflexural diaphragm elements, each of which is individually connected to terminals on the same printed circuit.

32. (New) A microphone component according to claim 27, further comprising a clip attached across the elastic metal disc for removably fixing the microphone component in a cavity while simultaneously establishing an electrical ground connection to said disc.

33. (New) A microphone component according to claim 19, wherein all of said elements are circular and coaxial.

34. (New) A method for the manufacture of a microphone component comprising the steps of:

a) stamping an anisotropic tape element out of a sheet material,

b) centering the anisotropic tape element on a printed circuit,

c) centering a piezoelectric transflexural diaphragm element on the anisotropic tape element,

d) establishing electrical contact to electrodes of the piezoelectric transflexural diaphragm element,

e) securing the tape element and diaphragm element together.

35. (New) A method for the manufacture of a microphone component comprising the steps of:

a) stamping foam and tape elements out of sheet material

b) centering a double-sided adhesive tape element on a metal disc,

c) centering a first foam element on the double-sided adhesive tape element,

d) centering a printed circuit on the first foam element with a conductor of the printed circuit facing the foam element,

e) centering an anisotropic tape element on the printed circuit,

f) centering a piezoelectric transflexural diaphragm element on the anisotropic tape element, establishing electrical contact to electrodes of the piezoelectric transflexural diaphragm element,

g) centering a double-sided adhesive tape element on a metal back of the piezoelectric transflexural diaphragm element, and

h) centering a second foam element on the double-sided adhesive tape element.

36. (New) A method for the manufacture of a microphone component comprising the steps of:

a) stamping foam and tape elements out of sheet material

b) centering a first foam element on a double-sided adhesive tape element,

c) centering the double-sided adhesive tape element on a metal back of a piezoelectric transflexural diaphragm element,

d) centering the piezoelectric transflexural diaphragm element on an anisotropic tape element, establishing electrical contact to electrodes of the piezoelectric transflexural diaphragm element,

e) centering the anisotropic tape element on a printed circuit,

f) centering the printed circuit on a second foam element with a conductor of the printed circuit facing the second foam element,

g) centering the second foam element on a double-sided adhesive tape element, and

h) centering the double-sided adhesive tape element on a metal disc.